

## Statement of Compliance

**Requested Part** 

10 December 2015

775210-000

(Part 1 of 1)

## S01-03-R

Part Status:	Active
Mil-Spec Certified:	M83519/1-3
EU RoHS/ELV Code:	Not EU RoHS or ELV Compliant
Solder Process Capability Code:	Not applicable for solder process capability
China RoHS:	Bestricted Materials Above Threshold

Exemptions: Exemptions Not Applicable

Each REACH declaration statement below refers ONLY to the specific SVHCs published to the REACH Candidate List on the Month/Year indicated. TE does not currently provide a cumulative REACH statement related to the most recent Date of Inclusion, or to the total number of substances on the Candidate List.

REACH Oct 2008 SvHC Compliance:	Contains no REACH October 2008 SvHC(s)
REACH Jan/Mar 2010 SvHC Compliance:	Contains no REACH Jan/Mar 2010 SvHC(s)
REACH June 2010 SvHC Compliance:	Contains no REACH June 2010 SvHC(s)
REACH December 2010 SvHC Compliance:	Contains no REACH December 2010 SvHC(s)
REACH June 2011 SvHC Compliance:	Contains no REACH June 2011 SvHC(s)
REACH December 2011 SvHC Compliance:	Contains no REACH December 2011 SvHC(s)
REACH June 2012 SvHC Compliance:	Contains no REACH June 2012 SvHC(s)
REACH December 2012 SvHC Compliance:	Contains no REACH December 2012 SvHC(s)
REACH June 2013 SvHC Compliance:	Contains no REACH June 2013 SvHC(s)
REACH December 2013 SvHC Compliance:	Contains no REACH December 2013 SvHC(s)
REACH June 2014 SvHC Compliance:	Contains no REACH June 2014 SvHC(s)
REACH December 2014 SvHC Compliance:	Contains no REACH December 2014 SvHC(s)

The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hex chrome, mercury, PBB, PBDE, and 0.01% for cadmium, or qualify for an exemption to above limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Note that any exemptions taken in this case would not include application specific exemptions (e.g. lead in solder for servers) as TE cannot determine where component products will be used.

Additionally, the part numbers that are as 5 of 6 compliant meet the material limits described above, except that these products have lead in the solderable interface only. These products may be suitable for use in an application that has an exemption for the use of lead in solder (e.g. servers, network infrastructure, etc).

Finished electrical and electronic products will be CE marked as required by Directive 2011/65/EU (RoHS2). Components may not be CE marked.

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information provided by our suppliers. This information is subject to change.



REACH June 2015 SvHC Compliance: Contains no REACH June 2015 SvHC(s) Halogen Content: Not Yet Reviewed for halogen content



Guy Degrieck Manager, Product Environmental Compliance

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10 December 2015

## 中国电子电气产品中有害物质的名称及含量

## China EEP Hazardous Substance Information

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Restricted Materials Above Threshold

部件名称 (Component Name)		有害物质 Hazardous Substance							
775210-000	铅 (Pb)	汞 (Hg)	镉 (Cd)	六价铬 (Cr6)	多溴联苯 (PBB)	多溴二苯醚 (PBDE)			
连接器系统 (Connector Systems)	x	0	0	Ο	0	0			
本表格依据SJ/T	11364标准的规定编	制。	This table is	compiled acc	ording to SJ/T	11364 standard			
Indicates that	贡在该部件所有均质 the concentration o vant threshold of th	f the hazardou	us substance in			of the part is			
Indicates that	贡至少在该部件的靠 the concentration o he relevant threshc	f the hazardou	us substance ir	n at least one l		-			
	电子电气产品的印	不保使用期限依	t据SJ/T 11388	标准的规定确定	定。				
Т	he EPUP value of	EEP is defined	d according to s	SJ/T 11388 st	andard				

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